

AMENDMENT OF CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. (Previously Presented) A plasma processing apparatus comprising:
 - a chamber defining at least one opening and constructed for retaining a generated plasma;
 - a dielectric member positioned to sealingly cover the at least one opening;
 - at least one wave guide provided exteriorly of the chamber such that one end side thereof opposes the dielectric member;
 - an electromagnetic wave source operatively coupled to the at least one wave guide;
 - a plurality of holes defined by a side of the at least one wave guide that is in opposition to the dielectric member; and
 - hole area adjusting means including a reciprocatable plate portion provided in at least one, but not all, of the plurality of holes to adjust the opening area of the at least one hole and thereby modulate the waveform of the a propagating wave during operation thereof.
2. (Previously Presented) A plasma processing apparatus according to claim 1, wherein at least one hole having the hole area adjusting means has a larger area than the areas of at least some of the other holes.
3. (Previously Presented) A plasma processing apparatus according to claim 2, wherein the hole having the larger hole area is located on the terminal end side of the wave guide.
4. (Original) A plasma processing apparatus according to claim 1, wherein the at least one wave guide includes a plurality of wave guides.
5. (Original) A plasma processing apparatus according to claim 1, wherein at least

one of the holes is located near the periphery of the dielectric member.

6. (Previously Presented) A plasma processing apparatus according to claim 1, wherein the at least one wave guide has a rectangular cross-sectional shape, the at least one hole has four sides of a rectangular shape, the dielectric member has four sides of a rectangular shape, and wherein the long sides of the at least one hole are parallel to one side of the dielectric member close thereto.

7. (Previously Presented) A plasma processing apparatus according to claim 1, wherein a hole area of a hole adjacent a side wall surface side of the chamber is made the largest, and wherein said hole is provided with the hole area adjusting means.

8. (Original) A plasma processing apparatus according to claim 1, wherein the hole area adjusting means is provided with a metal plate-like portion so as to adjust the opening area of the hole by reciprocating the plate-like portion.

9. (Canceled)

10. (Canceled)

11. (Canceled)

12. (Canceled)

13. (Canceled)